



# DEPARTMENT OF COMPUTER SYSTEM ENGINEERING

Digital Integrated Circuits - ENCS333

**Dr. Khader Mohammad**

**Lecture #5**

Design Matrices and Logic Design

# Digital Integrated Circuits

Course topics and Schedule	
	Subject
1	Introduction to Digital Integrated Circuits Design
2	Semiconductor material: pn-junction, NMOS, PMOS
3	IC Manufacturing and Design Metrics CMOS
4	Transistor Devices and Logic Design The CMOS inverter
5	<b>Design Matrices and Combinational logic structures</b>
6	Sequential logic gates; Latches and Flip-Flops
7	Layout of an Inverter and basic gates
8	Parasitic Capacitance Estimation
9	Device modeling parameterization from I-V curves.
	Short Test
10	Arithmetic building blocks
11	Interconnect: R, L and C - Wire modeling
12	Timing Power dissipation;
13	SPICE Simulation Techniques ( Project )
14	Memories and array structures
	Midterm
15	Clock Distribution
16	Supply and Threshold Voltage Scaling
17	Reliability and IC qualification process
18	Advanced Voltage Scaling Techniques
19	Power Reduction Through Switching Activity Reduction
20	CAD tools and algorithms
21	Final & Project discussion

# DIGITAL GATES

## Fundamental Parameters

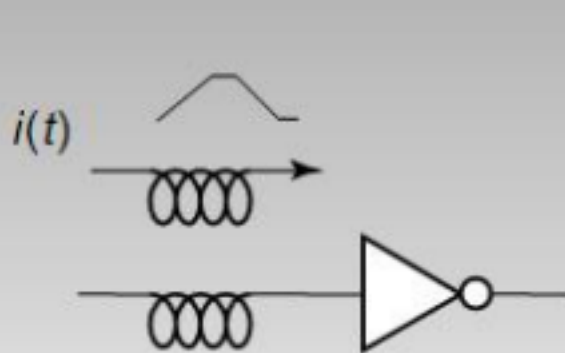
- Functionality
- Reliability, Robustness
- Area
- Performance
  - Speed (delay)
  - Power Consumption
  - Energy

# *Design Metrics*

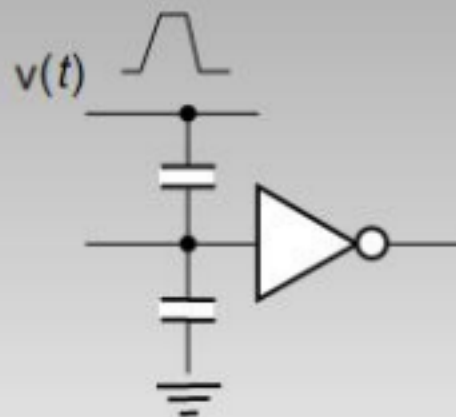
- How to evaluate performance of a digital circuit (gate, block, ...)?
  - Cost
  - Reliability
  - Speed/Performance (delay, frequency)
  - Power

# Reliability

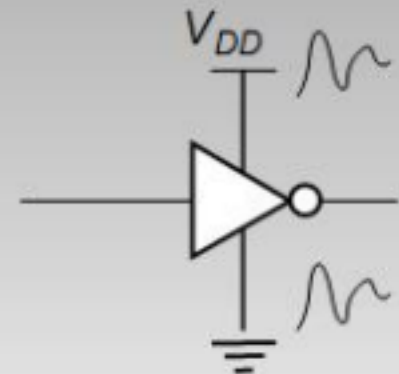
- The real world is analog
  - All physical quantities you deal with as a circuit designer are actually continuous
  - Thus, even a “digital” signal can be noisy:



Inductive coupling



Capacitive coupling



Power and ground noise

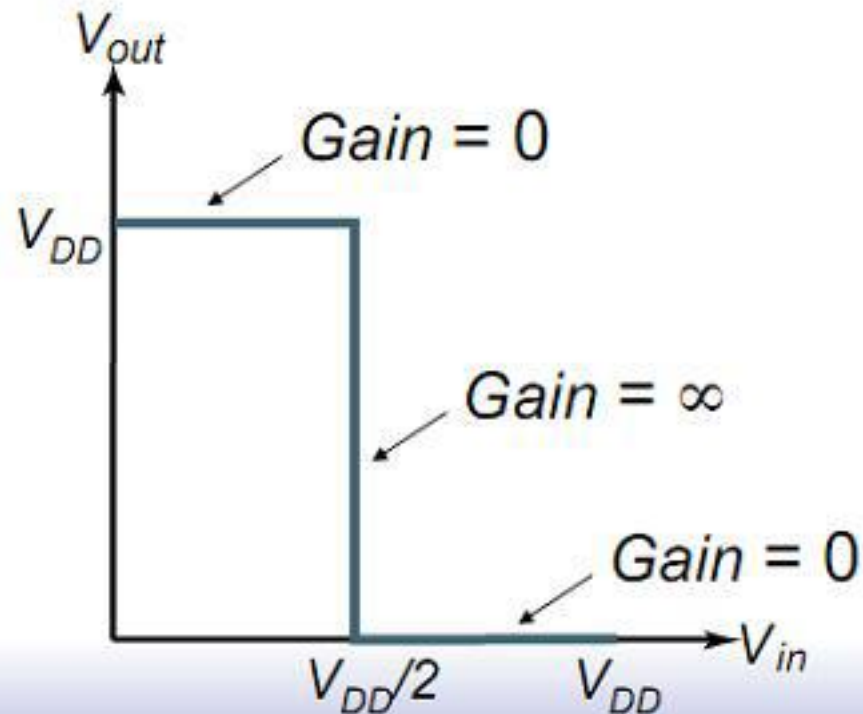
# Noise and Digital Systems

- Circuit needs to work despite “analog” noise
  - Digital gates can reject noise
  - This is actually how digital systems are defined
- Digital system is one where:
  - Discrete values mapped to analog levels and back
  - All the elements (gates) can reject noise
    - For “small” amounts of noise, output noise is less than input noise
  - Thus, for sufficiently “small” noise, the system acts as if it was **noiseless**

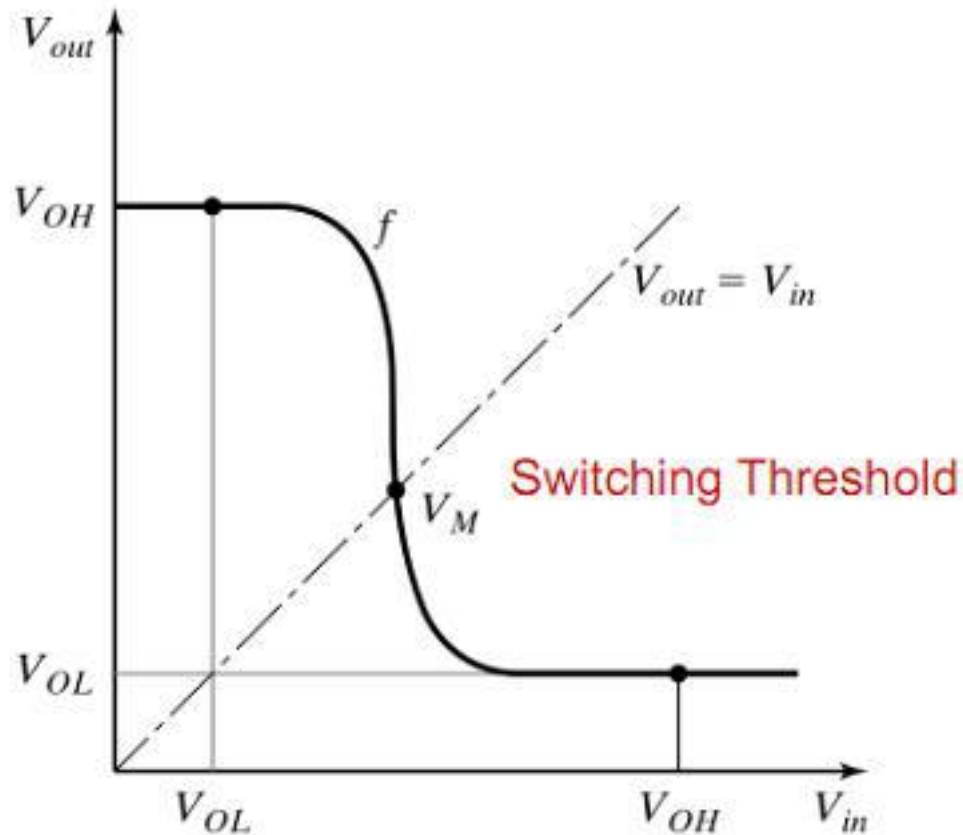
# Noise Rejection

- To see if a gate rejects noise
  - Look at its DC voltage transfer characteristic (VTC)
  - See what happens when input is not exactly 1 or 0

- Ideal digital gate:
  - Noise needs to be larger than  $V_{DD}/2$  to have any effect on gate output



# More Realistic VTC

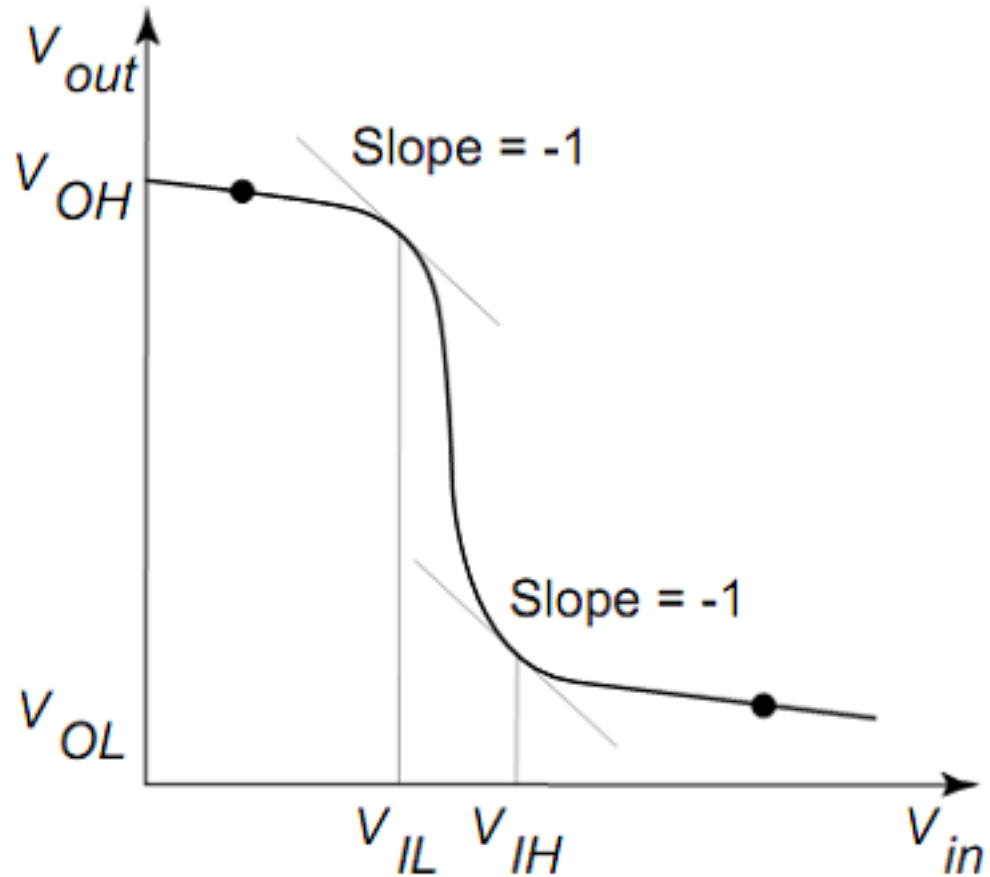
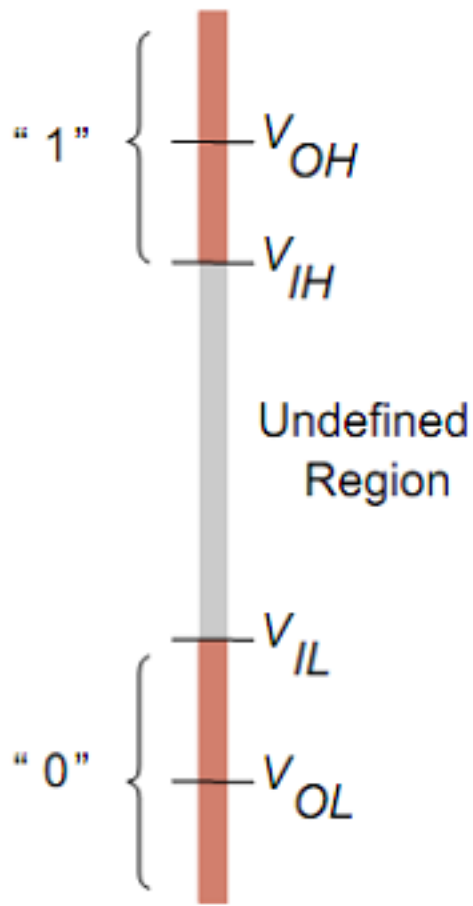


$$\begin{aligned} V_{OH} &= f(V_{OL}) \\ V_{OL} &= f(V_{OH}) \\ V_M &= f(V_M) \end{aligned}$$

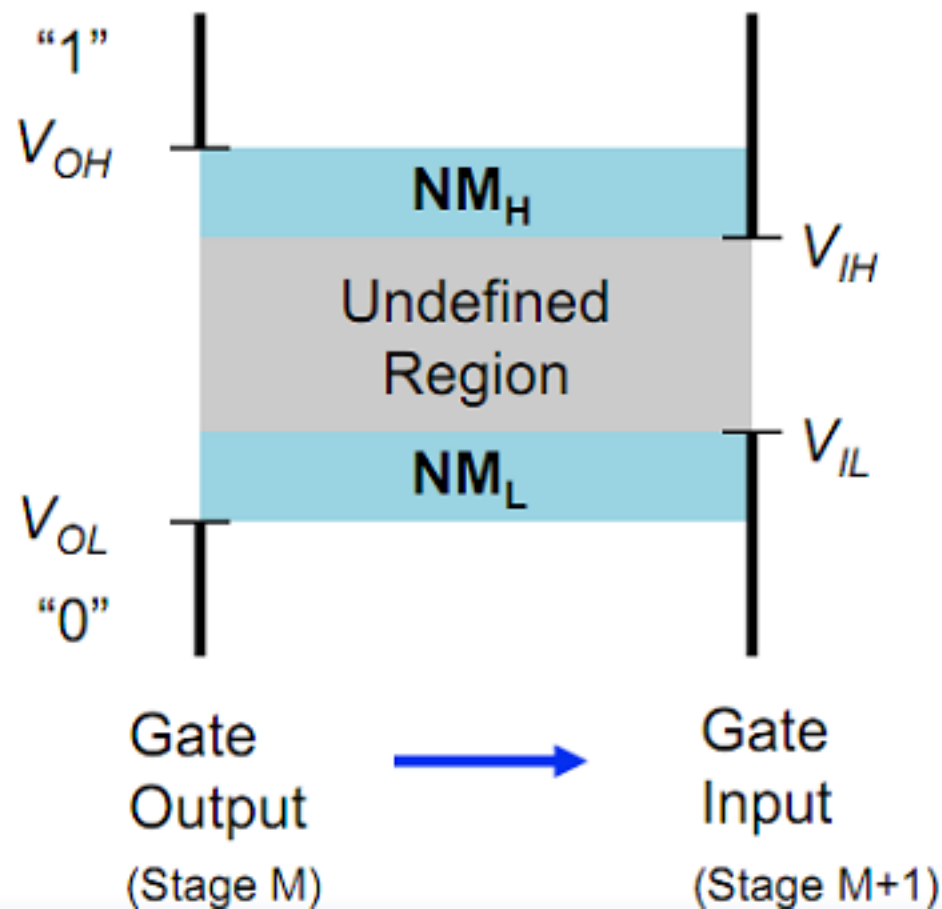
Nominal Voltage Levels



# Voltage Mapping



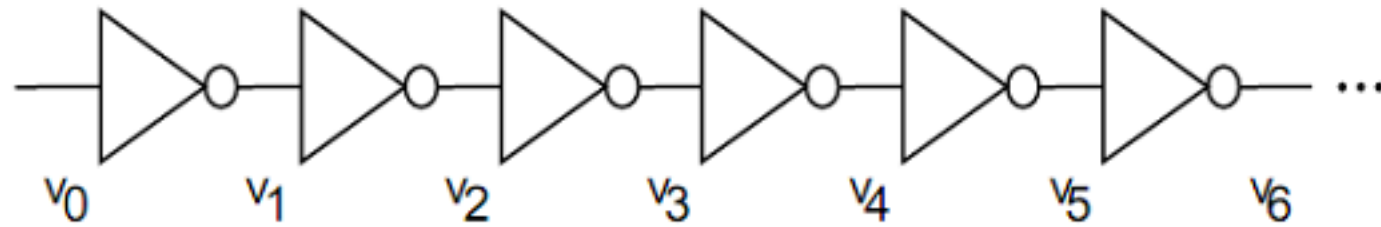
# Definitions of Noise Margins



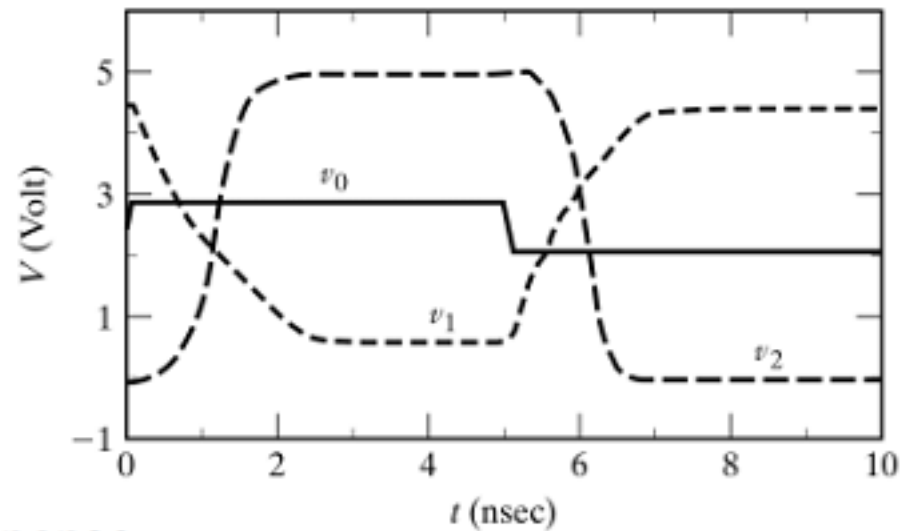
Noise margin high:  
 $NM_H = V_{OH} - V_{IH}$

Noise margin low:  
 $NM_L = V_{IL} - V_{OL}$

# Digital Noise Reduction: Regenerative Property

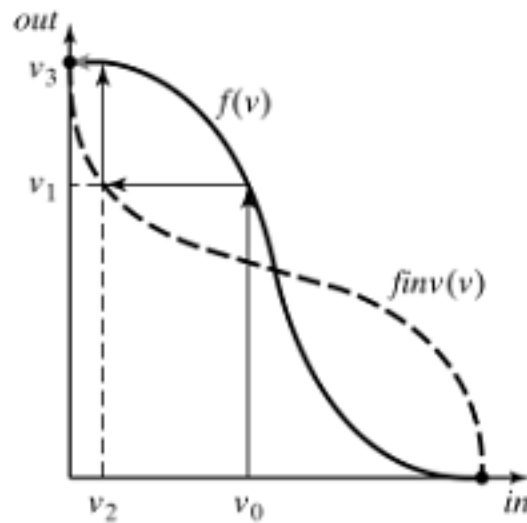


A chain of inverters

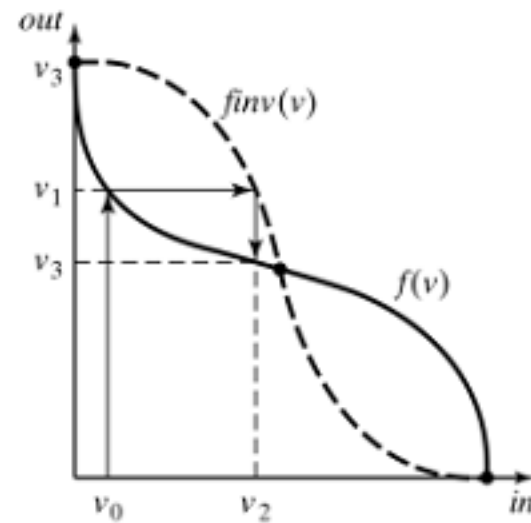


Simulated response

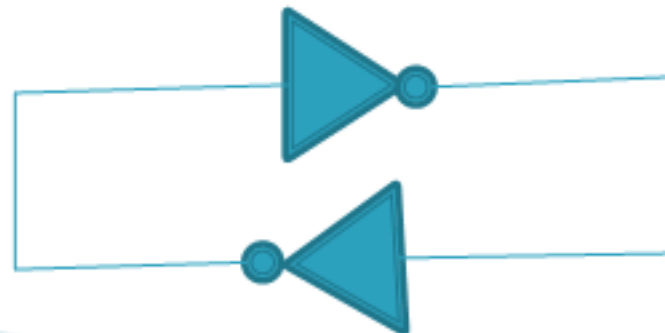
# Regenerative Property



Regenerative



Non-Regenerative



# Example

- $V_{OH} = 3.6V$
- $V_{OL} = 0.4V$
- $V_{IL} = 0.6V$
- $V_{IH} = 2.3V$
- $NM_H = V_{OH} - V_{IH} = 1.3V$
- $NM_L = V_{IL} - V_{OL} = 0.2V$

# Summery

- Understanding the design metrics that govern digital design is crucial
  - We discussed cost and reliability so far
  
- Key design messages so far:
  - Keep chip area as small as possible
  - Pick design styles and parameters so that noise margins are reasonable
  
- Summary of some key reliability metrics:
  - Noise transfer functions & margin (ideal: gain =  $\infty$ , margin =  $V_{dd}/2$ )
  - Output impedance (ideal:  $R_o = 0$ )
  - Input impedance (ideal:  $R_i = \infty$ )

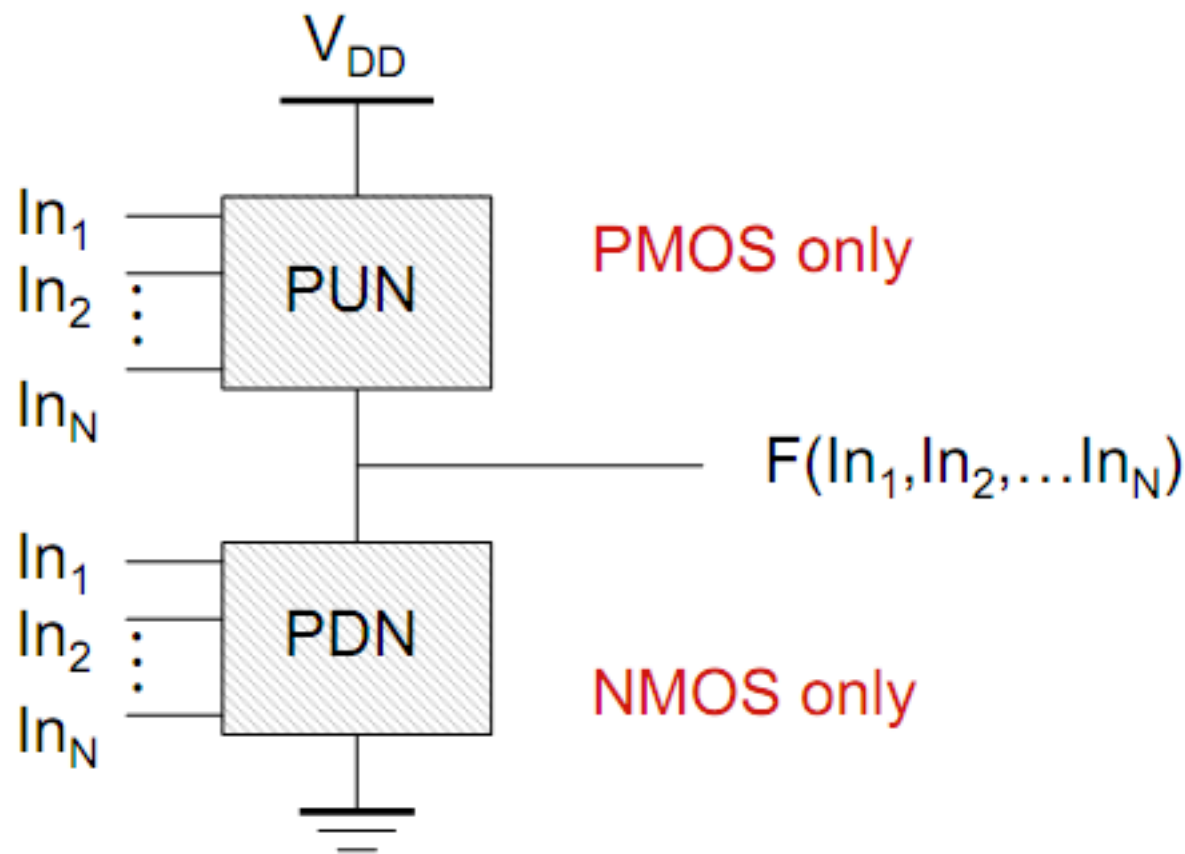
# Static Logic Gates

At every point in time (except during the switching transients) each **gate output is connected to either  $V_{DD}$  or  $V_{SS}$**  via a low resistive path.

The outputs of the gates **assume at all times the value of the Boolean function** implemented by the circuit (ignoring, once again, the transient effects during switching periods).

(Will contrast this later to **dynamic** circuit style.)

# Static Complementary CMOS



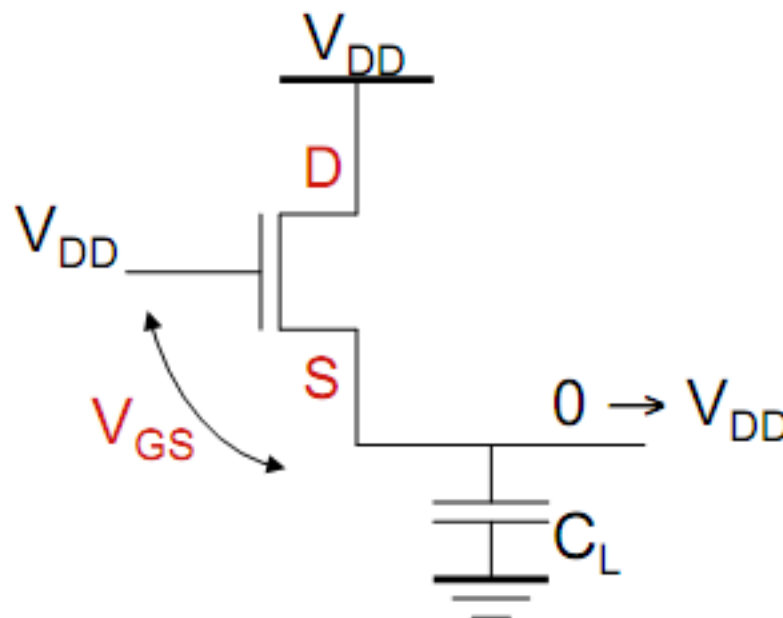
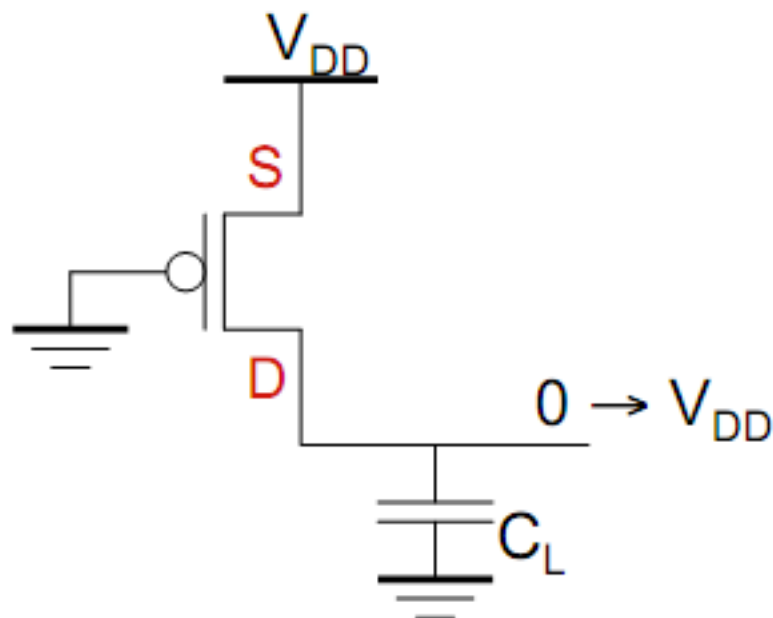
PUN and PDN are **dual** logic networks

PUN and PDN functions are **complementary**

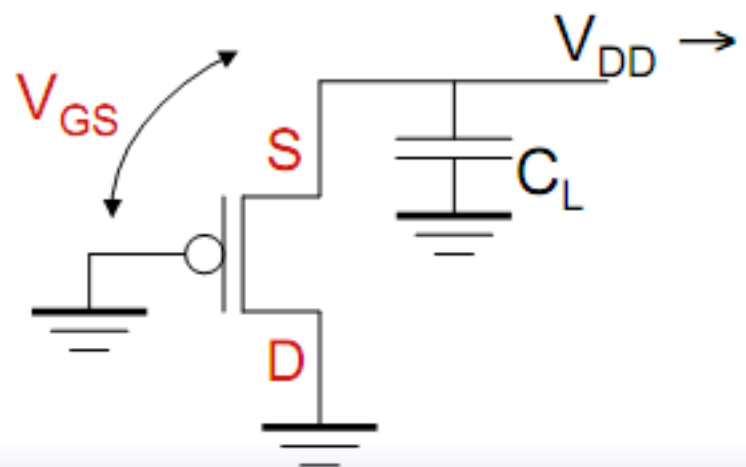
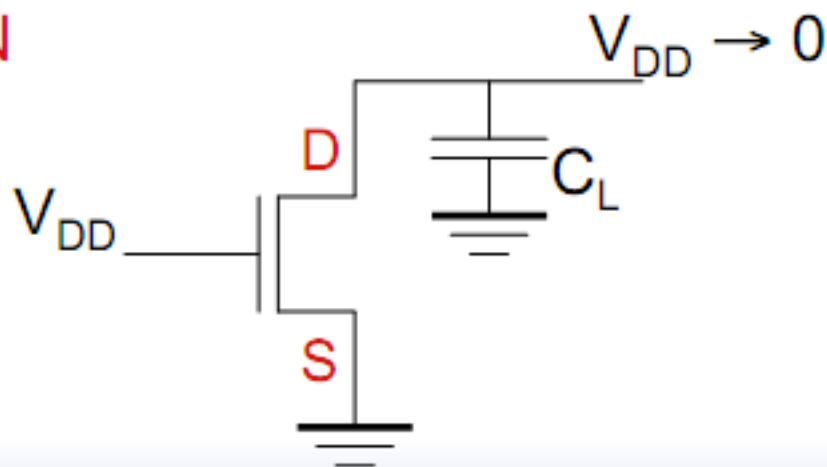


# REMEMBER ....

PUN

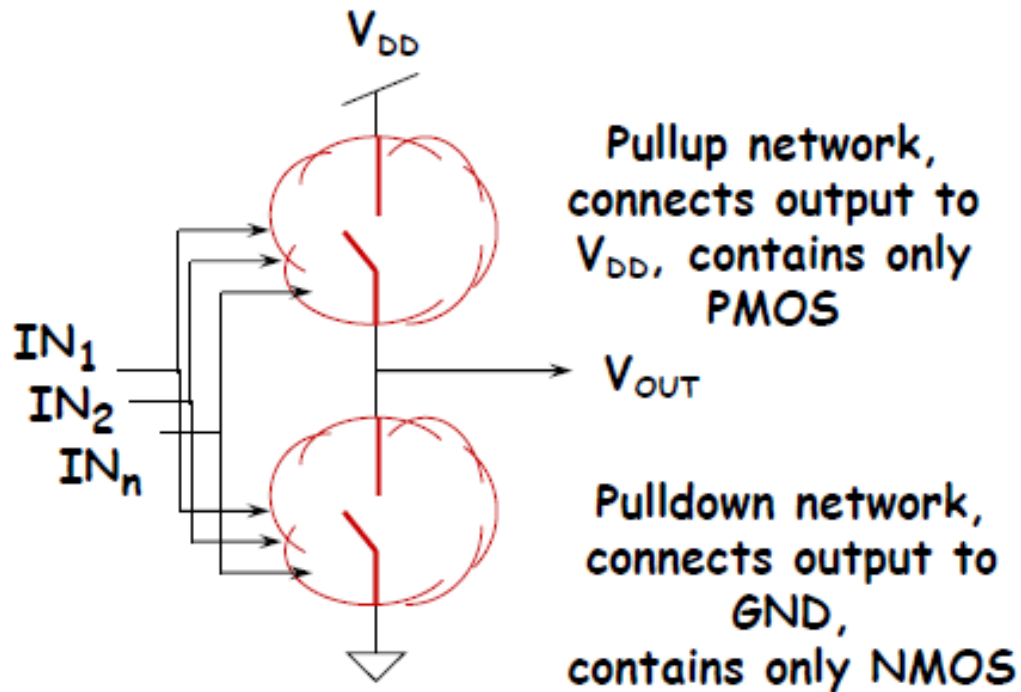


PDN



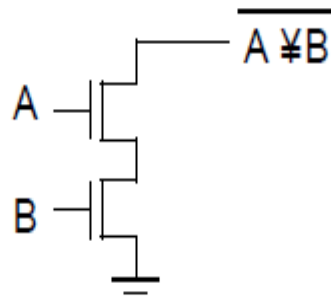
# Generic Static CMOS Gate

- For every set of input logic values, either pullup or pulldown network makes connection to  $V_{DD}$  or  $GND$
- If both connected, power rails would be shorted together
- If neither connected, output would float (tristate logic)

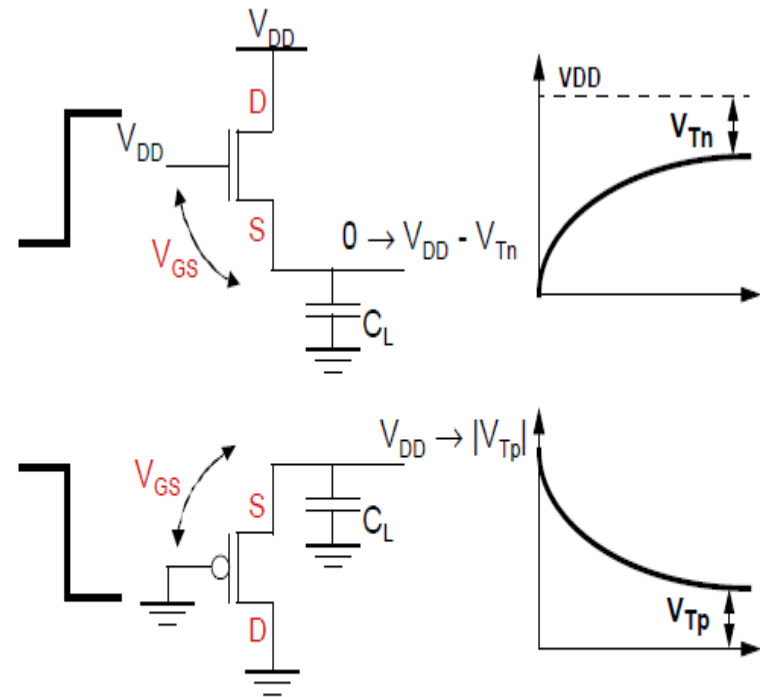
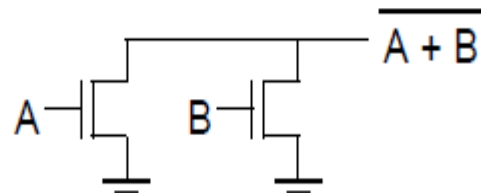


# Basic Logic

NMOS devices in **series**  
implement a **NAND** function



NMOS devices in **parallel**  
implement a **NOR** function

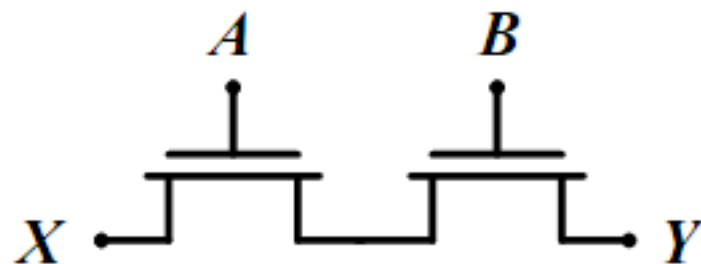


NMOS **will not** pass a "1"  
PMOS **will not** pass a "0"

# NMOS Transistors in Series/Parallel Connection

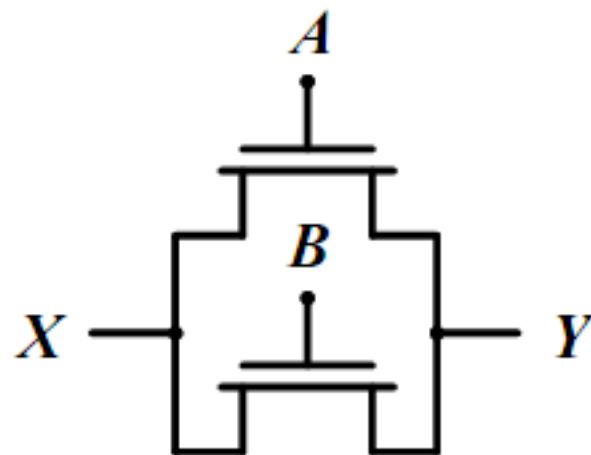
- Transistor  $\leftrightarrow$  switch controlled by its gate signal
  - NMOS switch closes when switch control input is

**AND**



**$Y = X$  if  $A$  AND  $B$**

**OR**

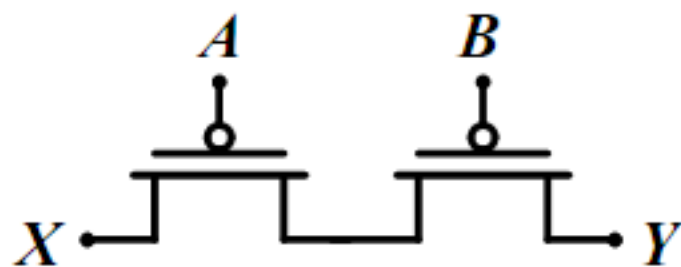


**$Y = X$  if  $A$  OR  $B$**

# PMOS Transistors in Series/Parallel Connection

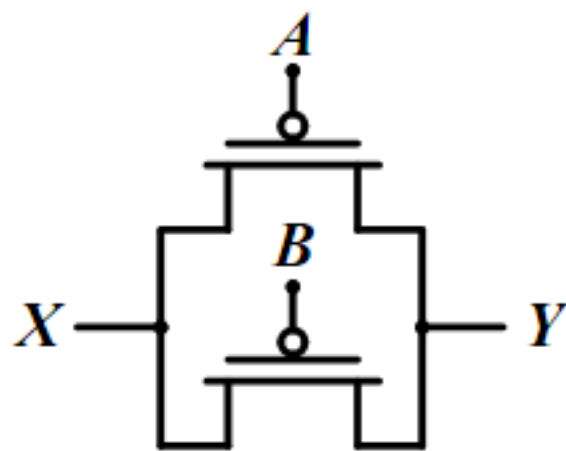
- PMOS switch closes when switch control is 1

**NOR**



$$Y = X \text{ if } \bar{A} \text{ AND } \bar{B} = 1$$

**NAND**



$$Y = X \text{ if } \bar{A} \text{ OR } \bar{B} = 1$$

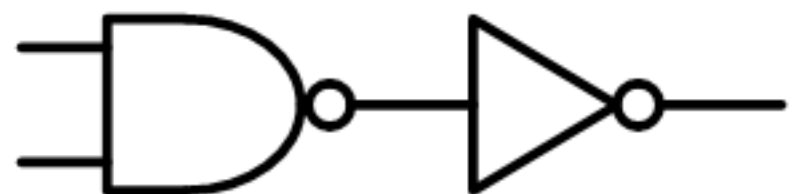
# Complementary CMOS Logic Style

- PUP is the **dual** to PDN  
(can be shown using DeMorgan's Theorems)

$$\overline{A + B} = \bar{A}\bar{B}$$

$$\overline{AB} = \bar{A} + \bar{B}$$

- Static CMOS gates are always inverting

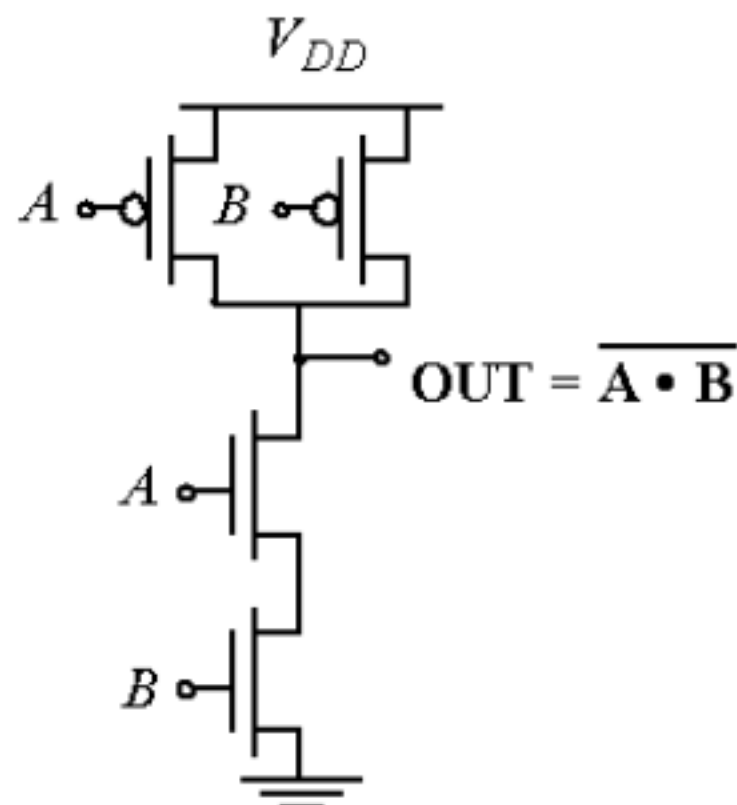


**AND = NAND + INV**

# Example Gate: NAND

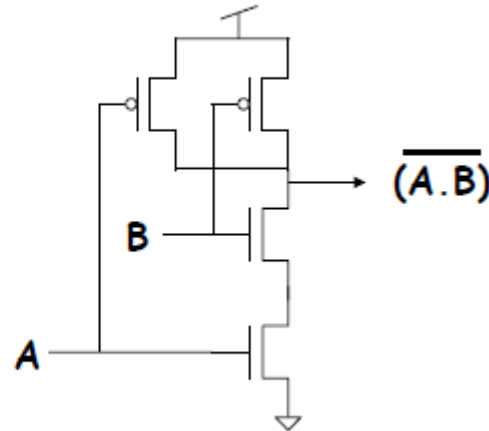
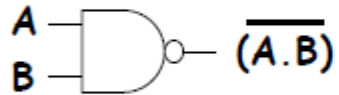
A	B	Out
0	0	1
0	1	1
1	0	1
1	1	0

Truth Table of a 2 input NAND gate



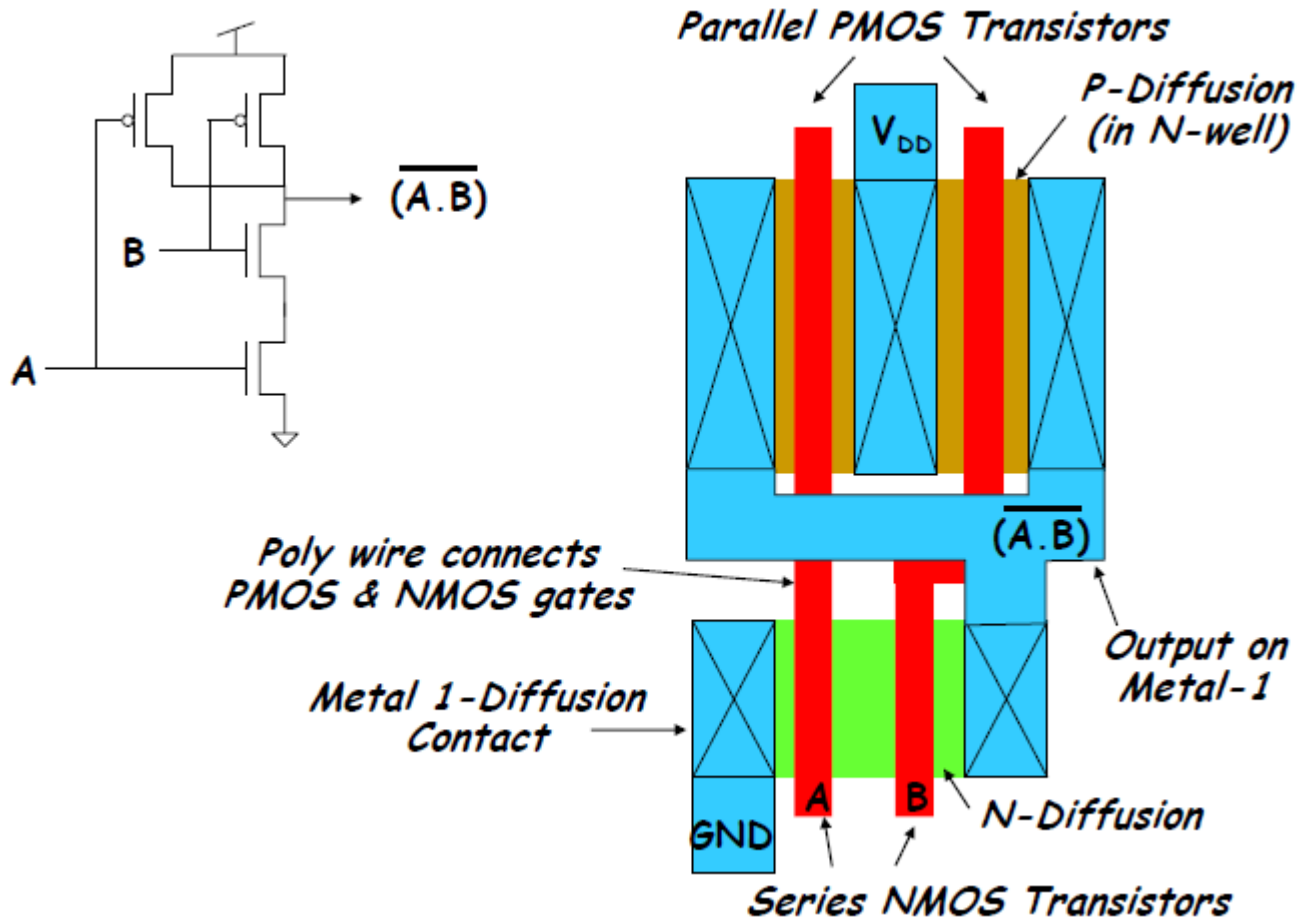
- PDN:  $G = \underline{AB} \Rightarrow$  Conduction to GND
- PUN:  $F = \overline{A + B} = \overline{AB} \Rightarrow$  Conduction to  $V_{DD}$
- $\overline{G(In_1, In_2, In_3, \dots)} \equiv F(\overline{In_1}, \overline{In_2}, \overline{In_3}, \dots)$

- **When both A and B are high, output is low. When either A or B is low, output is high**





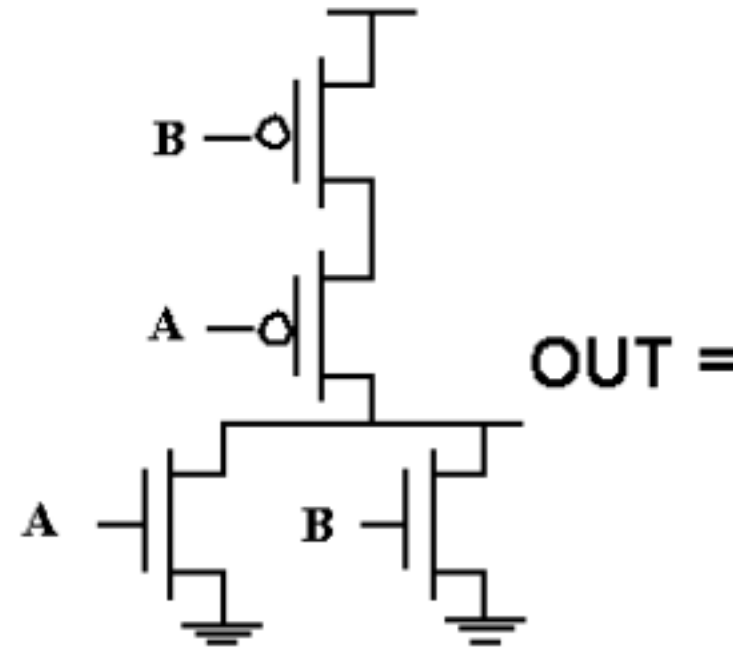
# NAND Gate Layout



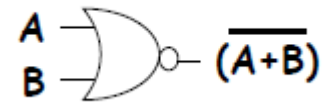
# Example Gate: NOR

A	B	Out
0	0	1
0	1	0
1	0	0
1	1	0

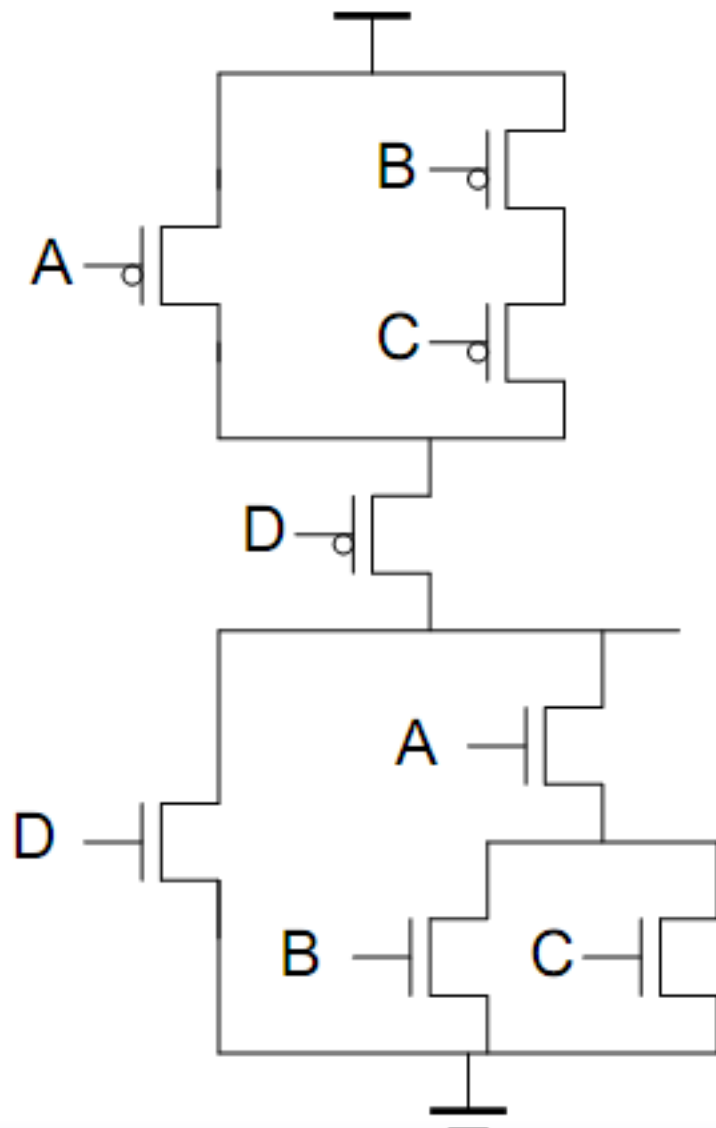
Truth Table of a 2 input NOR gate



When both A and B are low, output is high  
When either A or B is high, output is low



# Complex CMOS Gate



$$\text{OUT} = \overline{D + A \cdot (B + C)}$$

# CMOS Properties

- ❑ Full rail-to-rail swing
- ❑ Symmetrical VTC
- ❑ Propagation delay function of load capacitance and resistance of transistors
- ❑ No static power dissipation
- ❑ Direct path current during switching

# Pullup is Dual of Pulldown Network

For NAND gate,  $f = \overline{A \cdot B}$

Pulldown  $f = A \cdot B$

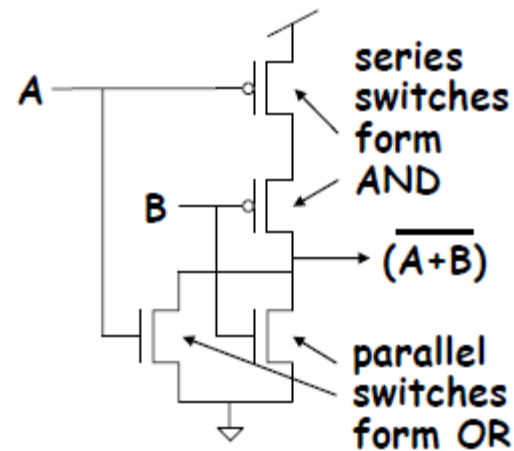
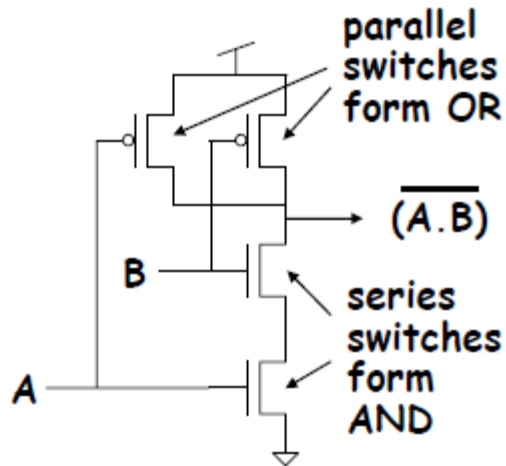
Pullup  $p = f = \overline{A \cdot B}$   
 $= \overline{A} + \overline{B}$

*(De Morgan's Laws)*

For NOR gate,  $f = \overline{A + B}$

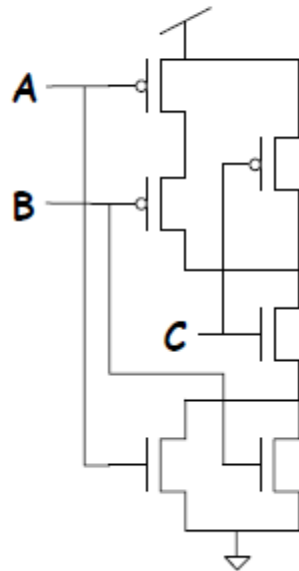
Pulldown  $f = A + B$

Pullup  $p = f = \overline{A + B}$   
 $= \overline{A} \cdot \overline{B}$



# More Complex Example

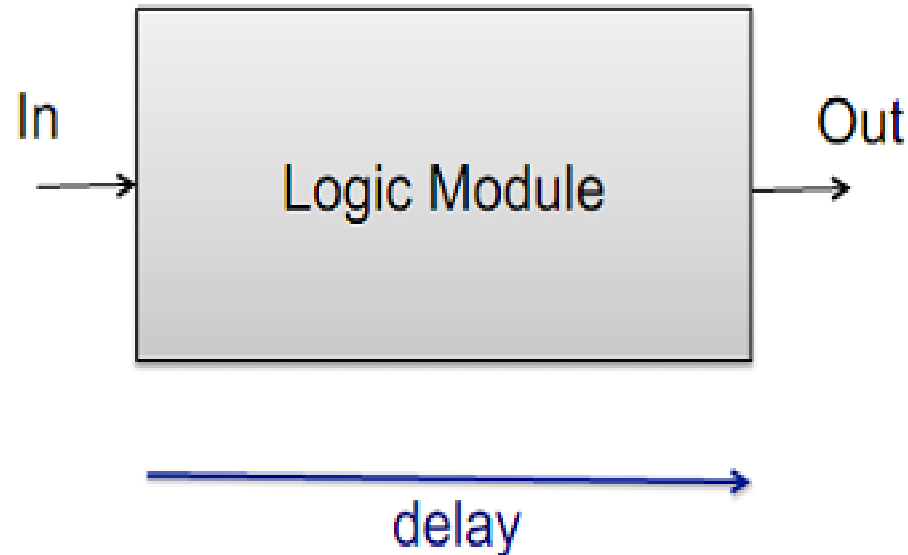
$$f = \overline{(A+B).C}$$



$$\begin{aligned} \text{pullup } p &= \overline{(A+B).C} \\ &= \overline{(A+B)} + \overline{C} \\ &= (\overline{A}.\overline{B}) + \overline{C} \end{aligned}$$

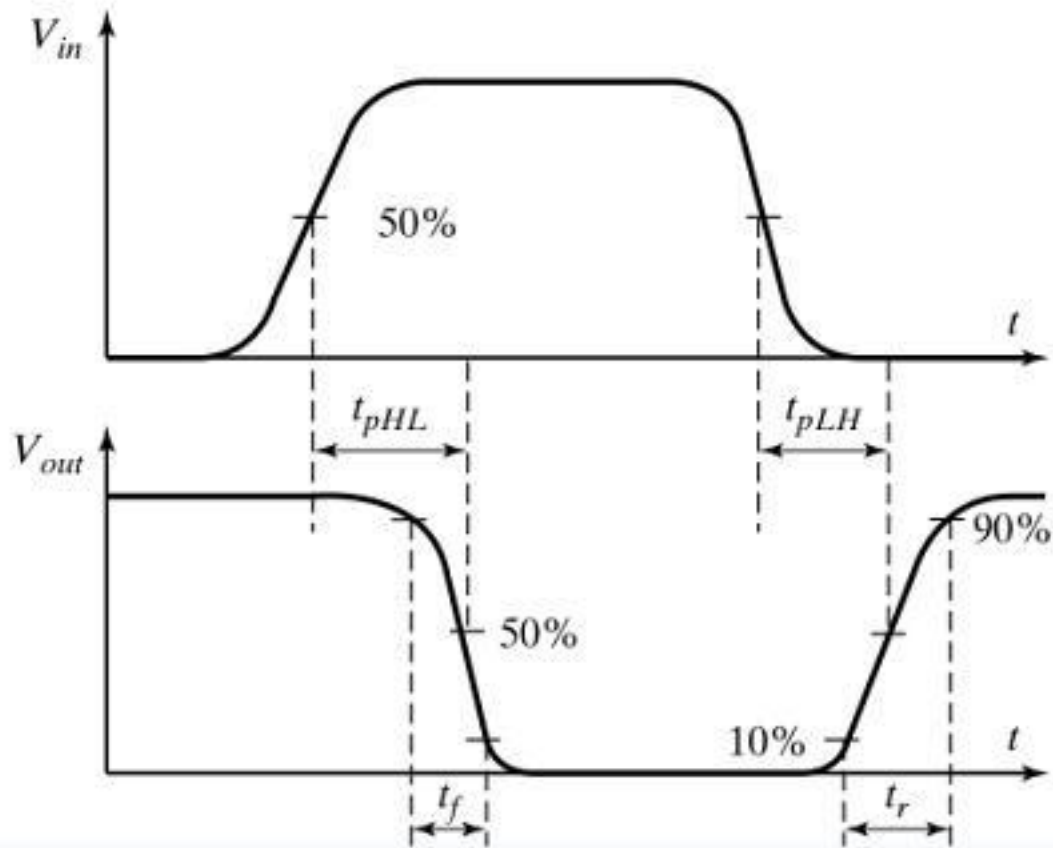
$$\text{pulldown } \overline{f} = (A+B).C$$

# *Primary Performance Metric: Delay*



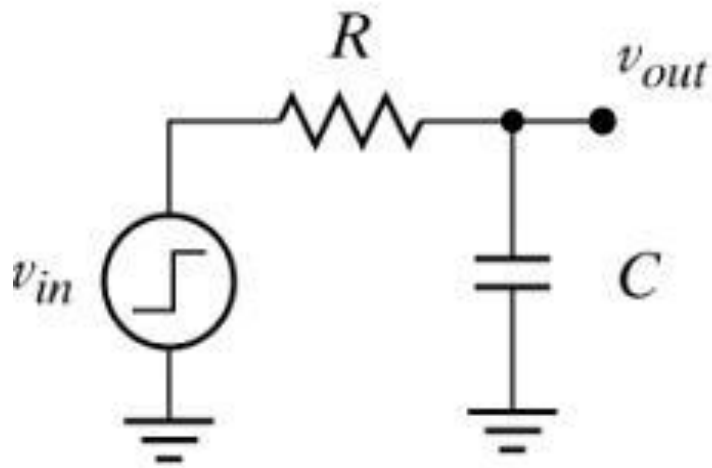
*How to define delay in a universal way?*

# Delay Definitions





# A First-Order RC Network



$$v_{out}(t) = (1 - e^{-t/\tau}) V$$



$$t_p = \ln(2) \tau = 0.69 RC$$

**Important model – matches delay of an inverter**

# Power Dissipation

Instantaneous power:

$$p(t) = v(t)i(t) = V_{supply}i(t)$$

Peak power:

$$P_{peak} = V_{supply}i_{peak}$$

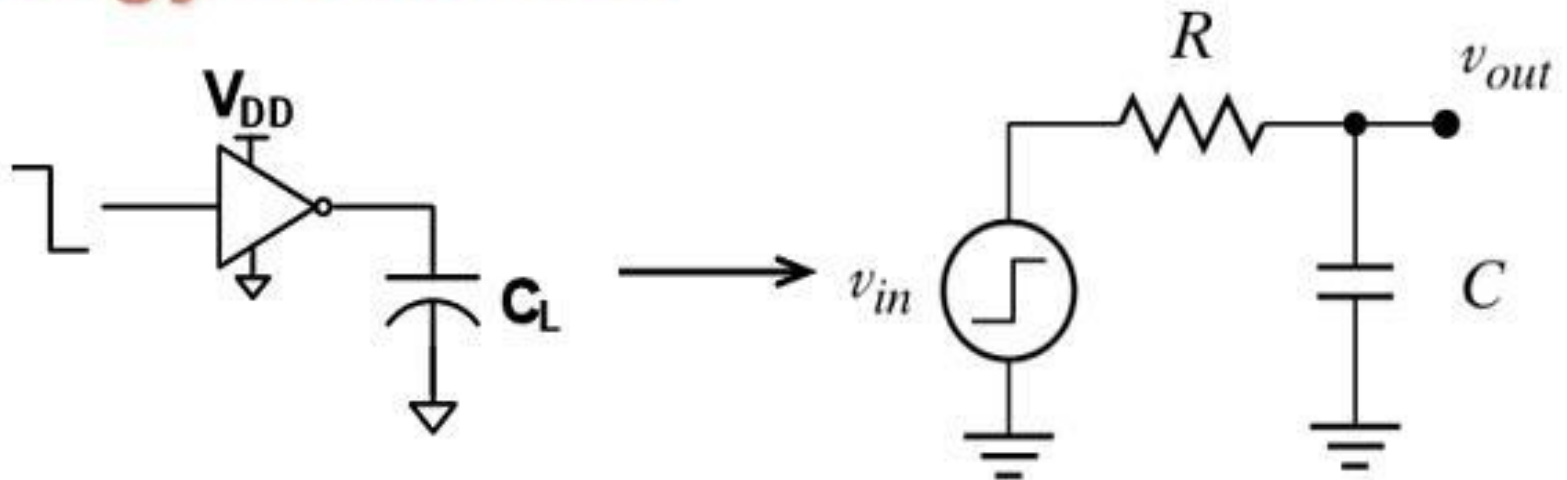
Average power:

$$P_{ave} = \frac{1}{T} \int_t^{t+T} p(t) dt = \frac{V_{supply}}{T} \int_t^{t+T} i_{supply}(t) dt$$

# “Power-Delay” and Energy-Delay

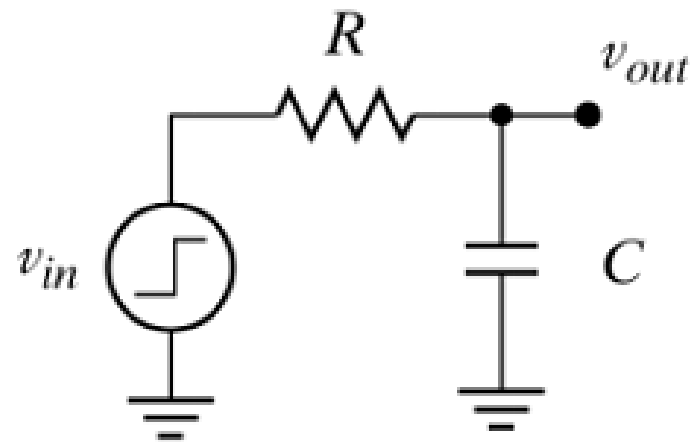
- Want low power and low delay, so how about optimizing the product of the two?
  - So-called “Power-Delay Product”
- Power·Delay is by definition Energy
  - Optimizing this pushes you to go as slow as possible
- Alternative gate metric: Energy-Delay Product
  - $EDP = (P_{av} \cdot t_p) \cdot t_p = E \cdot t_p$

# Energy in CMOS



- The voltage on  $C_L$  eventually settles to  $V_{DD}$
- Thus, charge stored on the capacitor is  $C_L V_{DD}$ 
  - This charge has to flow out of the power supply
- So, energy is just  $Q \cdot V_{DD} = (C_L V_{DD}) \cdot V_{DD}$

# Energy



$$E_{0 \rightarrow 1} = \int_0^T P_{DD}(t) dt = V_{DD} \int_0^T i_{DD}(t) dt = V_{DD} \int_0^{V_{DD}} C_L dv_{out} = C_L V_{DD}^2$$

$$E_C = \int_0^T P_C(t) dt = \int_0^T v_{out} i_L(t) dt = \int_0^{V_{DD}} C_L v_{out} dv_{out} = \frac{1}{2} C_L V_{DD}^2$$